



# SOT418-3

plastic, heatsink small outline package; 20 leads; low stand-off height, 1.27 mm pitch, 15.9 mm x 11.0 mm x 3.35 mm body

21 August 2018

Package information

## 1 Package summary

<b>Terminal position code</b>	D (double)
<b>Package type descriptive code</b>	HSOP20
<b>Package type industry code</b>	HSOP20
<b>Package style descriptive code</b>	HSOP (heatsink small outline package)
<b>Package body material type</b>	P (plastic)
<b>Mounting method type</b>	S (surface mount)
<b>Issue date</b>	23-07-2003
<b>Manufacturer package code</b>	SOT418

**Table 1. Package summary**

<b>Parameter</b>	<b>Min</b>	<b>Nom</b>	<b>Max</b>	<b>Unit</b>
package length	15.8	15.9	16	mm
package width	10.9	11	11.1	mm
seated height	-	3.5	-	mm
package height	3.2	3.35	3.5	mm
nominal pitch	-	1.27	-	mm
actual quantity of termination	-	20	-	



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2 Package outline

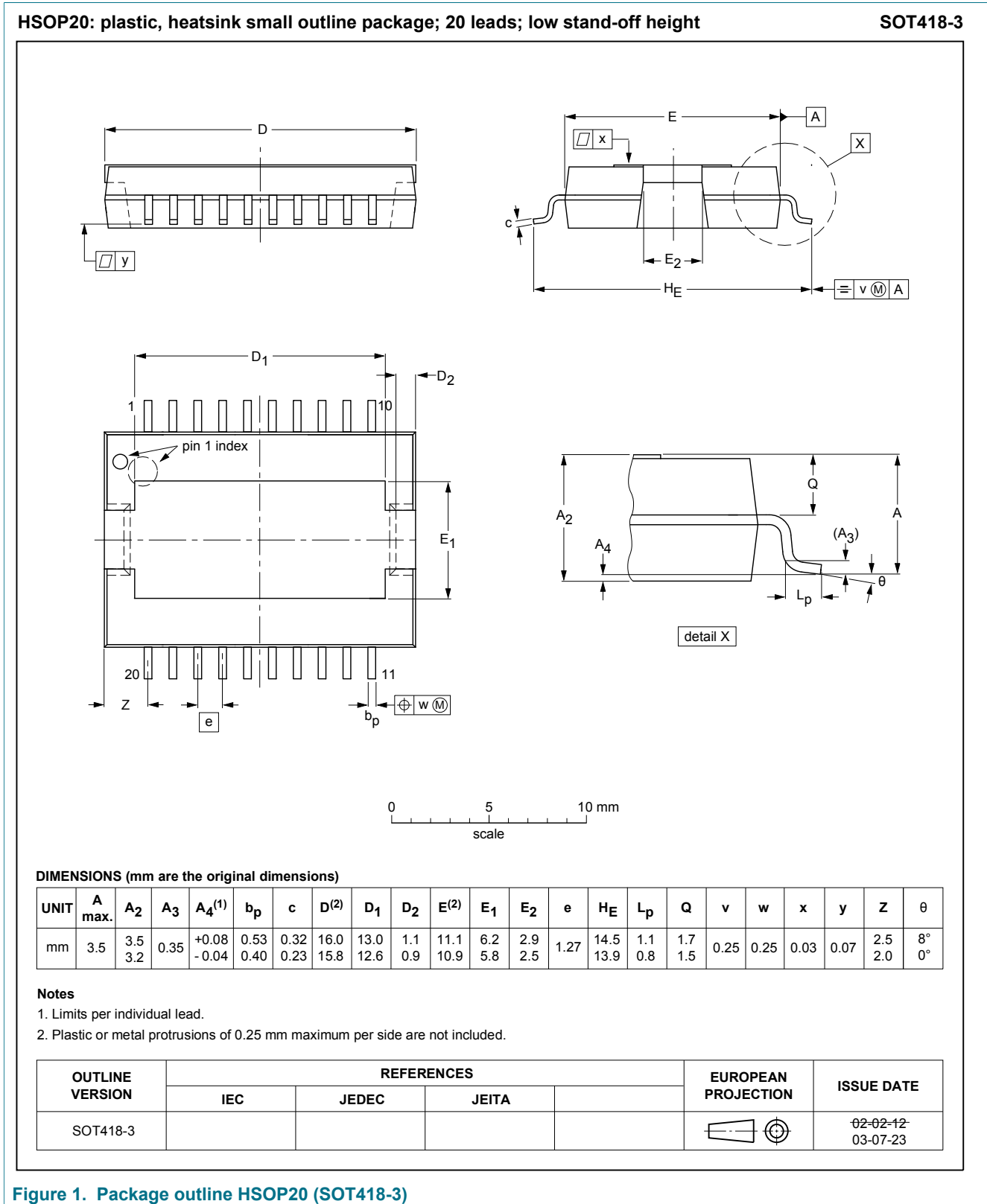


Figure 1. Package outline HSOP20 (SOT418-3)

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### 3 Legal information

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